

9/3/99

09-09-1999



101138737

The Honorable Commissioner of Patents and Trademarks  
Washington, D.C. 20231

UNITED STATES  
DEPARTMENT OF COMMERCE

Dear Sir:

Please record the attached original documents or copy thereof.

1. Name of Conveying party(ies): Teik Jin Tan<sup>1</sup>, Lam Cheow Aun<sup>2</sup>, and Ka Tiek Lim<sup>3</sup>

2. Name and Address of Receiving Party

State of Incorporation:

Motorola, Inc.,  
1303 East Algonquin Road  
Schaumburg, Illinois 60196

**Delaware**

3. Nature of Conveyance: Assignment Execution Date: September 9, 1995<sup>1</sup>, September 5, 1995<sup>2</sup>, and October 3, 1995<sup>3</sup>

4. This document is being filed for patent application:

Docket No.: CM07024X  
Title: A DIFFERENTIAL THICKNESS STENCIL  
Serial No.: 08/951,869 – Filed: October 16, 1997  
Continuation of Serial No.: 08/645,404 – Filed: May 13, 1996  
Issued as U.S. Patent No. 5,813,331 on September 29, 1998  
Based on Malaysia Patent Application No. PI9502828 – Filed September 22, 1995

The execution date of the application is: **December 18, 1995**

5. Please send correspondence to:

Motorola, Inc., Patent Department  
8000 West Sunrise Boulevard  
Ft. Lauderdale, Florida 33322

6. Total Number of application and patents involved: 1

7. Total Fee (37 CFR 3.41) \$ 40.00

8. Please charge to Deposit Account No.: 13-4774

9. To the best of my knowledge and belief, the foregoing information is a true and correct original document.

DO NOT USE THIS SPACE

SEND CORRESPONDENCE TO:

09/08/1999 NTHA11 00000150 134774 08951869  
01 FC:581 40.00 CH

Motorola, Inc.  
Intellectual Property Department  
8000 West Sunrise Boulevard  
Ft. Lauderdale, Florida 33322

By: Barbara R. Dautre  
Barbara R. Dautre  
Agent for Applicant(s)  
Reg. No.: 39,505  
Telephone: (954) 723-6449  
Fax No.: (954) 723-3871

Total Number of pages comprising cover sheet: 1  
Total Number of pages comprising Assignment: 5

Date: August 31, 1999

**ASSIGNMENT AND AGREEMENT**

For and in consideration of the sum of One Dollar to us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, we, **TEIK JIN TAN**, **LAM CHEOW AUN** and **KA TIEK LIM** of Malaysia, assigned and transferred, and do hereby sell, assign and transfer, unto MOTOROLA, INC., a corporation of the State of Delaware, having its principal office in Schaumburg, State of Illinois, United States of America, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions relating to improvement in **A DIFFERENTIAL THICKNESS STENCIL** (Case No. **CM07024X**), described, illustrated and claimed in an application for Letters Patent of the United States of America executed by us on the dates indicated by our signatures below, together with the entire right, title and interest in and to said application, and in and to Letters Patent which may be issued upon said application, and upon any division, extension, continuation or reissue thereof.

We hereby also sell, assign and transfer unto the said MOTOROLA, INC., the entire right, title and interest in and to said invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of said invention and said applications for Letters Patent in foreign countries, and we further authorize the said MOTOROLA, INC. to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing

date of the said application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to the said MOTOROLA, INC., for the sole use and behoof of said MOTOROLA, INC., its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted, the same as they would have been held and enjoyed by us had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to the said MOTOROLA, INC.

We agree that, when requested, we will, without charge to said MOTOROLA, INC., but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for said inventions in any and all countries and for vesting title thereto in said MOTOROLA, INC., its successors, assigns and legal representatives or nominees.

We covenant with said MOTOROLA, INC., its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

Date: 5-9-1995

*Handwritten signature*

TEIK JIN, TAN

Witness: *Cheang*

Name: LIH CHING, CHEANG

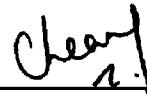
Witness: *Low*

Name: LAI YIN, LOW


Date: 5/9/95



LAM CHEOW, AUN

Witness: 

Name: LIH CHING, CHEANG

Witness: 

Name: LAI YIN, LOW

Date: 3/10/95

KA TIEK, LIM

KA TIEK, LIM

Witness: Cheang

Name: LIH CHING, CHEANG

Witness: <sup>pus</sup>

Name: LAI YIN, LOW